EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 11067520
PUBLICATION DATE : 09-03-99

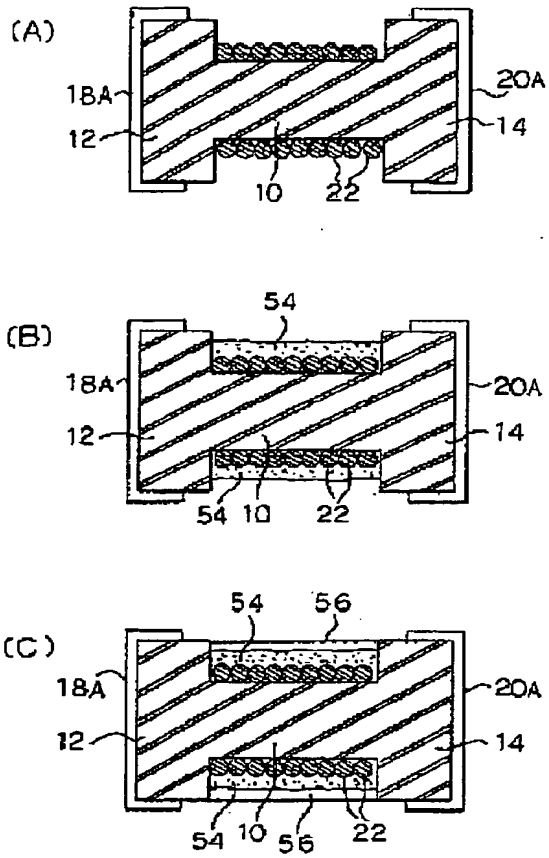
APPLICATION DATE : 19-08-97
APPLICATION NUMBER : 09237689

APPLICANT : TAIYO YUDEN CO LTD;

INVENTOR : HAGINO HIROSHI;

INT.CL. : H01F 5/06 H01F 1/37 H01F 17/04 H01F 27/32 H01F 37/00

TITLE : WIRE WOUND ELECTRONIC COMPONENT AND ITS SEALING RESIN



ABSTRACT : PROBLEM TO BE SOLVED: To stabilize the shape of wire wound electronic components by reducing the dimensional variation of the parts and, at the same time to improve the productivity of the parts by efficiently conducting applying work and marking work.

SOLUTION: After a conductor 22 is wound around a core 10, a ferrite- containing resin 54 and a conventional resin 56 are successively applied to the conductor 22. Therefore, the sealing resin of the conductor 22 has a two- layer structure of the resins 54 and 56. Since the outside layer of the sealing resin is composed of the conventional resin 56 having low viscosity and a high flow property, the sealing resin has a high leveling property after an application, and the applying work and molding work of the sealing resin can be conducted easily. In addition, the shape stability of the wire wound electronic components is improved, because the dimensional variation of the components is reduced. Moreover, the shock resistance of the outside layer of the sealing resin is improved, and marking on the outside layer is also facilitated.

COPYRIGHT: (C)1999,JPO

BEST AVAILABLE COPY